

TIDC-CC2650-CC2592-EMK

Revision: Rev 1.1.0

Part Reference	Quantity	Value	Description	MPN	Manufacturer	Part Number
A1	1	2.4GHz	ANTENNA, NON COMPONENT, 2.4GHZ INVERTED F ANTENNA, NOT APPLY	DN007	TEXAS INSTRUMENTS	13-00347
C1,C6	2	10uF	CAPACITOR, CERAMIC X5R, 10uF, 6.3V, -20%/+20%, -55DEGC/+85DEGC, 0603, SMD	GRM188R60J106ME47D	MURATA	02-02419
C2	1	1DNM	CAPACITOR, DO NOT MOUNT, 0603, SMD			02-01324
C3,C4,C5,C8,C9,C20	6	100nF	CAPACITOR, CERAMIC X7R, 100nF, 6.3V, -10%/+10%, -55DEGC/+125DEGC, 0402, SMD	GRM155R70J104KA01D	MURATA	02-02323
C7	1	100nF	CAPACITOR, CERAMIC X7R, 100nF, 25V, -10%/+10%, -55DEGC/+125DEGC, 0603, SMD	GRM188R71E104KA01D	MURATA	02-01992
C10,C15,C22,C23,C24,C29,C32	7	DNM_0402	CAPACITOR, CERAMIC, TBD, -55DEGC/+125DEGC, 0402, DNM, SMD	CAPACITOR_0402_DNM_N/A_M	MANUFACTURER SELECTION	02-04164
C11	1	2.2uF	CAPACITOR, CERAMIC X5R, 2.2uF, 10V, -20%/+20%, -55DEGC/+85DEGC, 0603, SMD	GRM188R61A225ME34D	MURATA	02-01132
C12,C13	2	2.2pF	CAPACITOR, CERAMIC C0G/NPO, 2.2pF, 50V, -0.25pF/+0.25pF, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H2R2CA01D	MURATA	02-04605
C14	1	1pF	CAPACITOR, CERAMIC C0G/NPO, 1pF, 50V, -0.25pF/+0.25pF, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H1R0CA01D	MURATA	02-04672
C16	1	1nF	CAPACITOR, CERAMIC X7R, 1nF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	CAPACITOR_0402_1nF_X7R_M_+/-5%_50V	MANUFACTURER SELECTION	02-03019
C17,C18	2	12pF	CAPACITOR, CERAMIC C0G/NPO, 12pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	CAPACITOR_0402_12pF_C0G/NPO_M_+/-5%_50V	MANUFACTURER SELECTION	02-03030
C19,C25	2	12pF	CAPACITOR, CERAMIC C0G/NPO, 12pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H120JA01D	MURATA	02-04168
C21,C28	2	1uF	CAPACITOR, CERAMIC X5R, 1uF, 10V, -10%/+10%, -55DEGC/+85DEGC, 0402, SMD	GRM155R61A105KE15D	MURATA	02-02381
C26	1	1nF	CAPACITOR, CERAMIC C0G/NPO, 1nF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	CAPACITOR_0402_1nF_C0G/NPO_M_+/-5%_50V	MANUFACTURER SELECTION	02-04728
C27	1	18pF	CAPACITOR, CERAMIC C0G/NPO, 18pF, 50V, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H180JA01D	MURATA	02-02407
C36,C37,C38	3	1.5pF	CAPACITOR, CERAMIC C0G/NPO, 1.5pF, 50V, -0.25pF/+0.25pF, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H1R5CA01D	MURATA	02-04678
DIO22	1	TP_0.9mm_PTH	NON COMPONENT, TEST POINT, HOLE 0.9mm, 1.5mm ETCH, PTH			19-00299
FIDU1,FIDU2,FIDU3,FIDU4,FIDU5,FIDU6	6	FIDU_1MM	NON COMPONENT, FIDUCIAL MARK, ROUND 1mm, SMD			19-00111
FL1,FL2	2	BLM18HE152SN1	FILTER, EMI, FERRITE BEAD, 1500@100MHz, -25%/+25%, -55DEGC/+125DEGC, 0603, SMD	BLM18HE152SN1D	MURATA	04-00470
J1	1	142-0711-201	CONNECTOR, COAX, RF, FEMALE, STRAIGHT, 1 PIN, SMD	142-0711-201	CINCH CONNECTIVITY	06-04996
L1	1	10uH	INDUCTOR, STANDARD, CHIP, FERRITE CORE, 10uH, -20%/+20%, 0.11A, -40DEGC/+85DEGC, 0805, SMD	CKS2125100M-T	TAIYO YUDEN	03-06514
L2	1	4.7nH	INDUCTOR, RF, CHIP, NON-MAGNETIC CORE, 4.7nH, -0.3nH/+0.3nH, 0.3A, -55DEGC/+125DEGC, 0402, SMD	LQG15HS4N7S02D	MURATA	03-06631
L3	1	TBD	INDUCTOR, STANDARD, CHIP, TBD, 0402, SMD	IND_TBD_0402	MANUFACTURER SELECTION	03-01022
L4	1	1nH	INDUCTOR, RF, CHIP, NON-MAGNETIC CORE, 1nH, -0.3nH/+0.3nH, 0.3A, -55DEGC/+125DEGC, 0402, SMD	LQG15HS1N0S02D	MURATA	03-06607
L13	1	2nH	INDUCTOR, RF, CHIP, NON-MAGNETIC CORE, 2nH, -0.3nH/+0.3nH, 0.3A, -55DEGC/+125DEGC, 0402, SMD	LQG15HS2N0S02D	MURATA	03-06525
P1,P2	2	SFM-110-02-S-D-A-K-TR	CONNECTOR, HEADER, FEMALE, STRAIGHT, 2 ROWS, 20 PINS, PITCH 1.27mm, SMD	SFM-110-02-SM-D-A-K-TR	SAMTEC	06-02251
R1	1	100k	RESISTOR, THICK FILM, 100k, -1%/+1%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	RESISTOR_0402_100k_+/-1%_50V_0.063W_M_+/-100ppm	MANUFACTURER SELECTION	01-12837
R2	1	3.9k	RESISTOR, THICK FILM, 3.9k, -1%/+1%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	RESISTOR_0402_3.9k_+/-1%_50V_0.063W_M_+/-100ppm	MANUFACTURER SELECTION	01-12675
R13,R14,R15	3	10k	RESISTOR, THICK FILM, 10k, -5%/+5%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	CRCW040210K0JNED	VISHAY	01-01244
SC1	1	BMIS-202-C	MECHANIC, COVER FOR SHIELD BMI-S-202	BMI-S-202-C	LAIRD	13-00498
SC2	1	BMIS-202-F	MECHANIC, FRAME FOR SHIELD BMI-S-202	BMI-S-202-F	LAIRD	13-00497
U1	1	CC2650F128RGZ	IC, MICROCONTROLLER, 2.4GHZ SIMPLELINK WIRELESS MCU, PITCH 0.5MM, QFN48, SMD	CC2650F128RGZT	TEXAS INSTRUMENTS	18-28499
U2	1	CC2592	IC, ANALOG, 2.4GHZ RF FRONT END, 2V TO 3.7V, QFN16, SMD	CC2592RGVT	TEXAS INSTRUMENTS	18-28661
Y1	1	32.768kHz	CRYSTAL, RESONATOR, 32.768kHz, -40DEGC/+85DEGC, SMD	FC-135 32.7680KA-AG0	EPSON	12-00546
Y2	1	24MHz	CRYSTAL, RESONATOR, 24MHz, -15PPM/+15PPM, -40DEGC/+85DEGC, SMD	TSX-3225 24.0000MF15X-AC3	EPSON	12-00757

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